

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/20/2022

Details for "BQ26500PW"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
BQ26500PW	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	PW 8	3x4.4x1.0	32.8

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000005	0.00757	76	0.000015	0
Precious Metals	Gold	7440-57-5	0.066044	99.99243	999924	0.201587	2016
Sub-Total			0.066049	100	1000000	0.201602	2016
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.021028	1.99997	20000	0.064184	642
Precious Metals	Silver	7440-22-4	0.725477	68.999996	690000	2.214385	22144
Thermoplastics	Epoxy	85954-11-6	0.304911	29.000034	290000	0.930685	9307
Sub-Total			1.051416	100	1000000	3.209254	32093
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	8.320218	95.197002	951970	25.395938	253959
Copper and Its Alloys	Iron	7439-89-6	0.00874	0.1	1000	0.026677	267
Magnesium and Its Alloys	Magnesium	7439-95-4	0.01311	0.15	1500	0.040016	400
Nickel and Its Alloys	Nickel	7440-02-0	0.3059	3.5	35000	0.933704	9337
Other Inorganic Materials	Silicon	7440-21-3	0.0437	0.5	5000	0.133386	1334
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000262	0.002998	30	0.00008	8
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.00437	0.05	500	0.013339	133
Zinc and Its Alloys	Zinc	7440-66-6	0.0437	0.5	5000	0.133386	1334
Sub-Total			8.74	100	1000000	26.677246	266772
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.114144	95.12	951200	0.348404	3484
Precious Metals	Gold	7440-57-5	0.000936	0.78	7800	0.002857	29
Precious Metals	Palladium	7440-05-3	0.00492	4.1	41000	0.015017	150
Sub-Total			0.12	100	1000000	0.366278	3663
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	16.441892	85.000002	850000	50.185857	501859
Other Plastics and Rubber	Carbon Black	1333-86-4	0.05803	0.299999	3000	0.177126	1771
Thermoplastics	Epoxy	85954-11-6	2.84348	14.7	147000	8.679201	86792
Sub-Total			19.343402	100	1000000	59.042184	590422
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.441136	100	1000000	10.503436	105034
Sub-Total			3.441136	100	1000000	10.503436	105034
Total			32.762003			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.